

Title (en)  
HIGH TEMPERATURE ANODIC BONDING APPARATUS

Title (de)  
GERÄT FÜR ANODISCHES HOCHTEMPERATUR-BONDING

Title (fr)  
APPAREIL DE COLLAGE ANODIQUE À HAUTE TEMPÉRATURE

Publication  
**EP 2013407 A4 20110518 (EN)**

Application  
**EP 07755626 A 20070418**

Priority  

- US 2007009423 W 20070418
- US 79397606 P 20060421
- US 41744506 A 20060503

Abstract (en)  
[origin: US2007246450A1] An anodic bonding apparatus includes: a first bonding plate mechanism operable to engage a first material sheet, and to provide at least one of controlled heating, voltage, and cooling thereto; a second bonding plate mechanism operable to engage a second material sheet, and to provide at least one of controlled heating, voltage, and cooling thereto; a pressure mechanism operatively coupled to the first and second bonding plate mechanisms and operable to urge the first and second bonding plate mechanisms toward one another to achieve controlled pressure of the first and second material sheets against one another along respective surfaces thereof; a control unit operable to produce control signals to the first and second bonding plate mechanisms and the pressure mechanism to provide heating, voltage, and pressure profiles sufficient to achieve anodic bonding between the first and second material sheets.

IPC 8 full level  
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Citation (search report)  

- [XD] US 2004229444 A1 20041118 - COUILLARD JAMES G [US], et al
- See references of WO 2007127111A2

Designated contracting state (EPC)  
DE FR GB IT

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